

**Amendment to the specification**

**Please replace the paragraph beginning at page 8, line 12, with the following amended paragraph.**

In this case, the reticle 101 and the reticle chuck 102 expand by thermal expansion in the conventional structure shown in FIGs. 7A and 7B, and the ~~reticle 101~~ reticle 101 and the reference surface 103 shift their positions. For example, if the reticle 101 and the reference surface 103 are spaced as shown in FIGs. 7A and 7B, the position of the reticle 101 is measured with error, because position shift of the reticle 101 and the reference surface 103 by the thermal expansion are different from each other and the position of the reticle 101 does not correspond to that of the reference surface 103 by temperature change. This measurement error causes imprecise transcription of the circuit pattern on the reticle to the wafer in exposure by scanning a reticle stage 104, and the problem of high fraction defective of a chip. The material of the reticle chuck cannot always have the coefficient of thermal expansion for using electrostatic suction type as the reticle chuck, and it makes the problem about thermal expansion big.